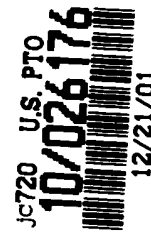


Express Mail No. EK140252521US
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Karen Cing-Mars 12/21/01
(Signature & date)



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of _____ : December 19, 2001
Soon-Cheon Seo et al. : Group Art Unit: 1741
Serial No. : Examiner: Hicks
Filed: : International Business Machines Corporation
2070 Route 52
Hopewell Junction, NY 12533

TITLE: METHOD FOR FORMING ENCAPSULATED METAL INTERCONNECT
STRUCTURES IN SEMICONDUCTOR INTEGRATED CIRCUIT DEVICES

INFORMATION DISCLOSURE STATEMENT

U.S.. Patent and Trademark Office
P.O. Box 2327
Arlington, VA 22202

Sir:

Pursuant to the duty of disclosure set forth in 37 C.F.R. 1.56, and further pursuant to the provisions of 37 C.F.R. 1.97 and 1.98, applicants hereby respectfully submit copies of the prior patents and publications as listed on Form PTO-1449, attached hereto.

In citing these documents, no representation is made nor intended as to the pertinency or non-pertinency of the art, that better art than that listed is not available, or that other art is not applicable.

Respectfully submitted,
Soon-Cheon Seo et al.

By Margaret A. Pepper
Margaret A. Pepper, Attorney
Registration No. 45,008
Telephone No. 845-894-4713

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

ATTY DOCKET NO.
FIS9-2001-0286-US1

SERIAL NO.

Soon-Cheon Seo et al.

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10/026176
2/21/01

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*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	4,810,332	03/07/1989	Pan			
	5,530,293	06/25/1996	Cohen et al.			
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						YES	NO
	JP11163523A	06/18/1999	Japan				

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

EXAMINER

DATE CONSIDERED

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U.S. PATENT DOCUMENTS

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							YES	NO

OTHER DOCUMENTS *(Including Author, Title, Date, Pertinent Pages, Etc.)*

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